

## VERSION SHOWING THE CHANGES TO THE ABSTRACT

Amend the abstract as follows:

~~Electronic component comprising predominantly organic functional materials and a process for the production thereof.~~

~~The invention concerns an electronic component comprising predominantly organic functional materials with improved through plating. The through plating is formed in the present case prior to application of the insulating layer, in the form of a free standing raised portion.~~

An electronic component comprises a plurality of layers at least two of which comprise predominantly organic functional materials with improved through-plating through certain of the layers. The through-plating is formed in one embodiment by a disruption element on a first lower layer which results in a void in the subsequently applied layers, which void is filled with a material which may be conductive to form the through plating. In a second embodiment, the through plating is formed on the first lower layer prior to the subsequent application of the other layers, in the form of a free-standing truncated frusto-conical raised portion, and forms a disruption or non-wetting element for the subsequently applied other layers, formed on the first lower layer and which are engaged with and surround the through plating after their application.